

**Amendments to the Drawings:**

Please replace Figures 1-3 with new Figures 1-3. A new drawing page containing Figures 1-3 is submitted herewith.

## Amendments to the Specification

On page 4, please amend the last paragraph as follows:

Figs. 2 and 3 are cross-sections of two embodiments of the bond pad structure of the semiconductor device of the present invention, wherein the upper cross-section A-A' of Figs. 2 and 3 are cross-sections of Fig. 1 indicated by cross-section view A-A' means of the upper arrow, while the lower cross-sections B-B' of Figs. 2 and 3 are cross-sections of Fig. 1 indicated by cross-section view B-B' means of the lower arrow.